

4

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DRG. NO. B-2518

SH 1 REV. A

1

D

D

74.000±.100
mm

149.000±.100
mm

C

C

B

B

A

A

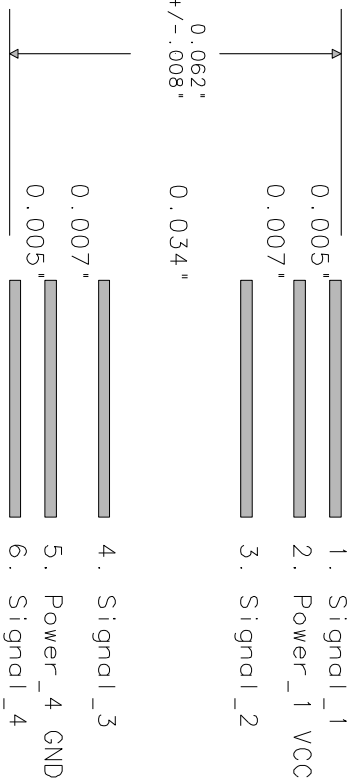
BOARD'S DRILL SCHEDULE

FHS [Inches]	COUNT	PLATED	COMMENT
.02	390	YES	
.041	67	YES	
.042	80	YES	
.0551	4	NO	
.057	2	YES	
.1063	8	NO	

Board Characteristics

- Dimensions are given in inches and mm;
- Material FR4,
- Min trace width: 0.006" on all layers;
- Min. clearance: 0.006" on all layers;
- 1 oz copper for top, bottom and power layers;
- 1/2 oz copper for embedded signal layers;
- Electroless Nickel/Immersion Gold plating. Apply soldermask;
- FHS tolerances: 0.002";
- Board thickness and inter-layer spacing as specified;
- Silkscreen on both sides;
- Trace impedance: 55 Ohm +/-5 Ohm for 0.006" traces on all layers;

Layer Order



QUESTIONS SPECIFIED DIMENSIONS ARE IN INCHES UNLESS OTHERWISE NOTED. DECIMALS .XX

ON NOT SCALE DRAWINGS

THE UNIVERSITY OF CHICAGO
Electronics Development Group

CONTRACT NO.	TITLE
APPROVALS	CDF Level 2 TAXI-Tx Board
DESIGNER: M. Bogdan	DATE: 11/12/02
CHECKER: M. Bogdan	DATE: 11/12/02
ISSUED	SIZE: FSCM NO.
FINISH	SCALE: B
SIMILAR TO	DRG. NO. B-2518
ACT. NO.	SHEET 1/1
CALC. NO.	REV. A

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